



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL21C103JBFNNNE
- Description : CAP, 10nF, 50V, ±5%, C0G, 0805

A. Samsung Part Number

			<u>CL</u> ①	<mark>21</mark> ②	<u>C</u> 3	<u>103</u> ④	<u>J</u> 5	<u>B</u> 6	<u>F</u> ⑦	<u>N</u> 8	<u>N</u> 9	<u>N</u> 10	<u>Е</u> 1		
-	Series Size	Samsung 0805	Multi-la	•	erami			r ± 0.1		mm		W:	1 25	± 0.1	mm
3	Dielectric	C0G		Juc)		L.	2.0 (8)	Inne			le	vv.	Ni	10.1	
4	Capacitance	10					0	Term	ninat				Cu	0 0/	<i></i>
5	Capacitance tolerance	±5	%				9	Plati Prod	•				Sn 10 Norma		(Pb Free)
6	Rated Voltage	50	V				10	Spec	ial				Reser	ved for	future use
\bigcirc	Thickness	1.25	± 0.1	mm			1	Pack	agir	ng			Embo	ssed T	ype, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1kltz±10% 0.5~5Vrms						
Q	1000 min							
Insulation	10,000Mohm or 500Mohm µF	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	300% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	COG							
Characterisitcs	(From -55 $\%$ to 125 $\%$, Capacitance change shoud be within ±30PPM/ $\%$)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change :	Bending to the limit (1mm)						
	within $\pm 5\%$ or ± 0.5 pF whichever is larger	with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120℃ for 10~30sec.)						
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger							
	Tan δ, IR : initial spec.							

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within ±2.5% or ±0.25pF whichever is larger	From 10H₂ to 55H₂ (return : 1min.)					
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 200 min						
	IR : 500Mohm or 25Mohm $\cdot \mu F$						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within $\pm 3\%$ or ± 0.3 pF whichever is larger	Max. operating temperature					
	Q : 350 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm $\cdot \mu F$						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	Min. operating temperature \rightarrow 25 °C					
	Tan δ, IR : initial spec.	\rightarrow Max. operating temperature \rightarrow 25 °C					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.